

Novel sensor technologies for tracking and vertexing:

A 2D position sensitive microstrip sensor with charge division.

A segmented p-type sensor with low-gain charge amplification.

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IFCA

Outline



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- Motivations for the R&D.
- A 2D position sensitive microstrip sensor.
 - _ Laser characterization
 - _ Electrical equivalent circuit simulations
 - _ Test beam results
- Segmented p-type sensors with low-gain charge amplification
 - _ TCAD simulations of the device.
 - _ Laser characterization of diodes with amplification.
- Conclusions

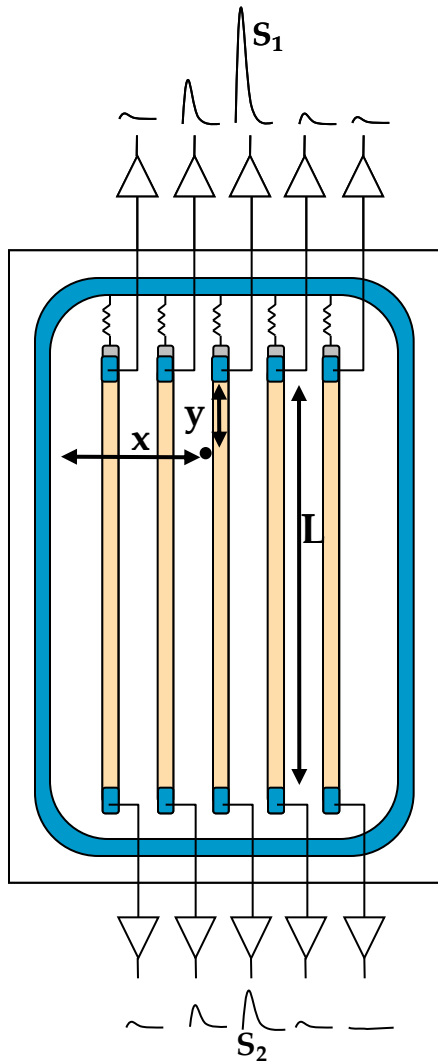
- Charge division in microstrips:
 - Long microstrips ladders (several tens of centimeters) proposed for the ILC tracking detectors.
 - Getting the particle hit coordinate along the strip using the charge division method.
 - Avoid the complexity of double sided sensors and the additional material of a second layer of sensors.
- Low gain segmented p-type pixels (strips)
 - Implementing a small gain in the segmented diode so we can reduce the thickness of the sensors without reducing the signal amplitude
 - Smaller contribution to the material budget.

Charge Division in uStrips

Simple single-side AC-coupled microstrip detectors
with resistive coupling electrodes.

X-coordinate: cluster-finding algorithms for strip detectors.

Y-coordinate: Resistive charge division method.



Resistive material
Aluminium

** Electrode resistance \gg preamplifier impedance.

$$S_1 = f(y)$$

$$S_2 = f(L - y)$$

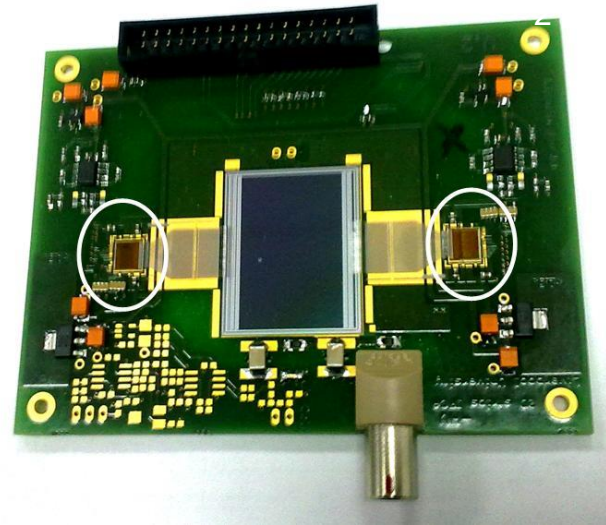
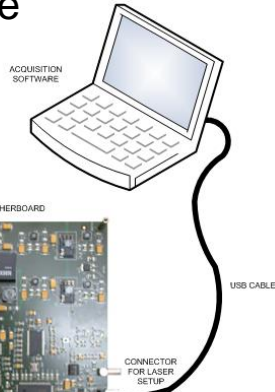
$$\frac{y}{L} = \frac{A_2}{A_1 + A_2}$$

Resistive material: high doped polysilicon

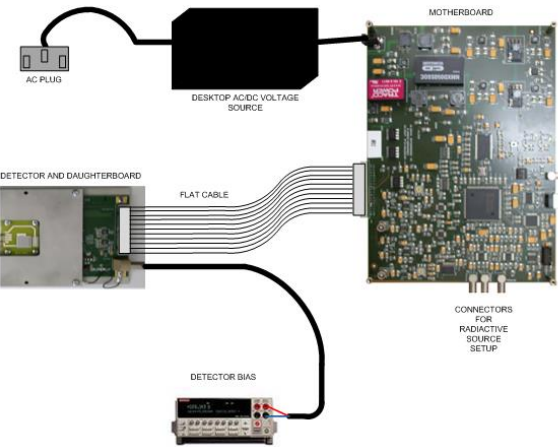
** V. Radeka, IEEE Transaction on Nuclear Science NS-21 (1974) 51

Proof-of-Concept Prototype

ALIBAVA DAQ system for microstrip detectors, based on the **Beetle** analogue readout ASIC



Strip:
length = 20 mm
width = 20 μ m
Pitches:
Implant = 80 μ m
readout = 80 μ m
Electrode:
 R/μ m = 2.8 Ohms/ μ m
 R/μ m = 12.2 Ohms/ μ m



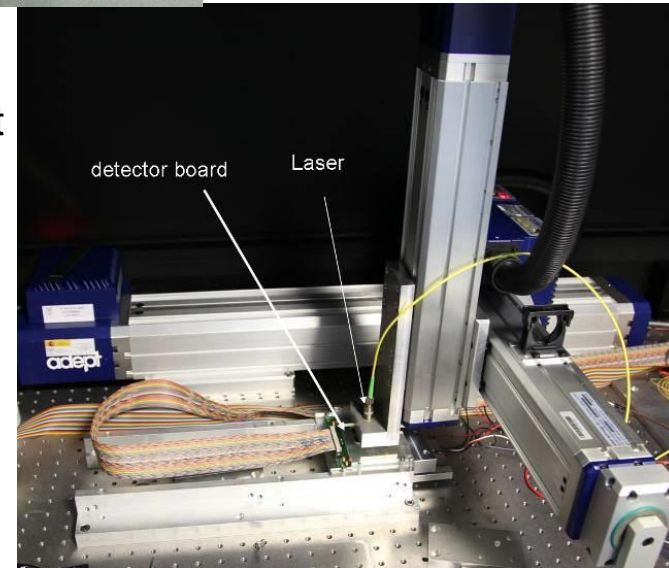
3D axis stage with displacement accuracy $\approx 10 \mu$ m

Pulsed DFB laser
 $\lambda = 1060$ nm

- 256 channels
- peaking time = 25ns
- $S/N \approx 20$ for standard no irradiated detectors

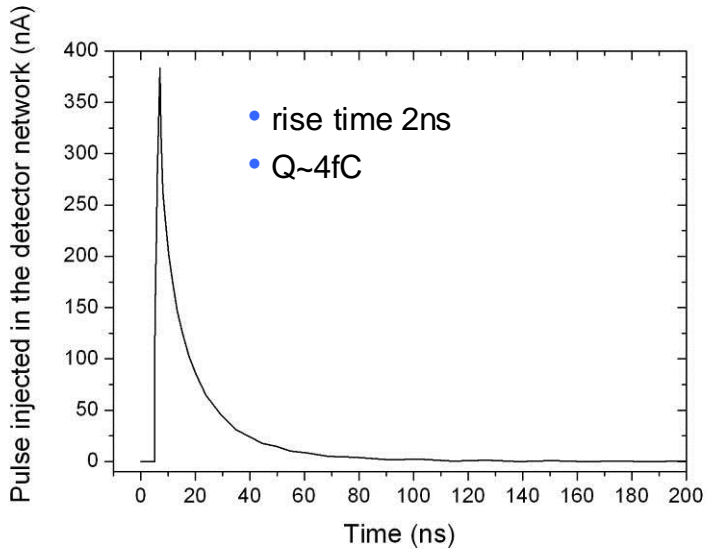
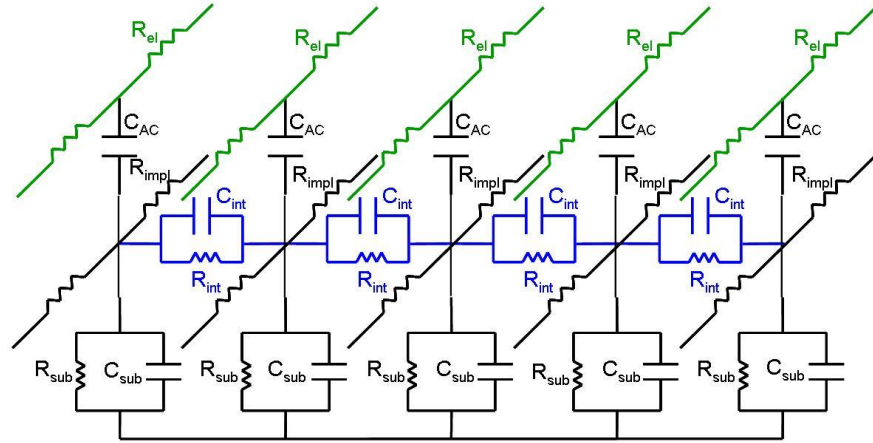
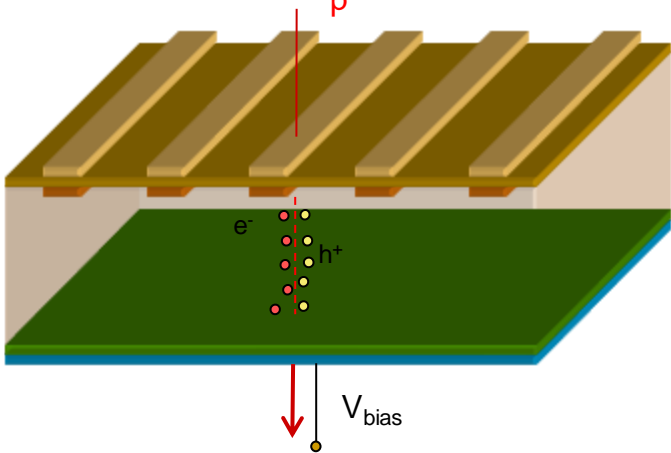
- Gaussian beam spot width $\approx 15 \mu$ m
- pulse duration 2ns

Clean room laboratory at IFCA, Santander

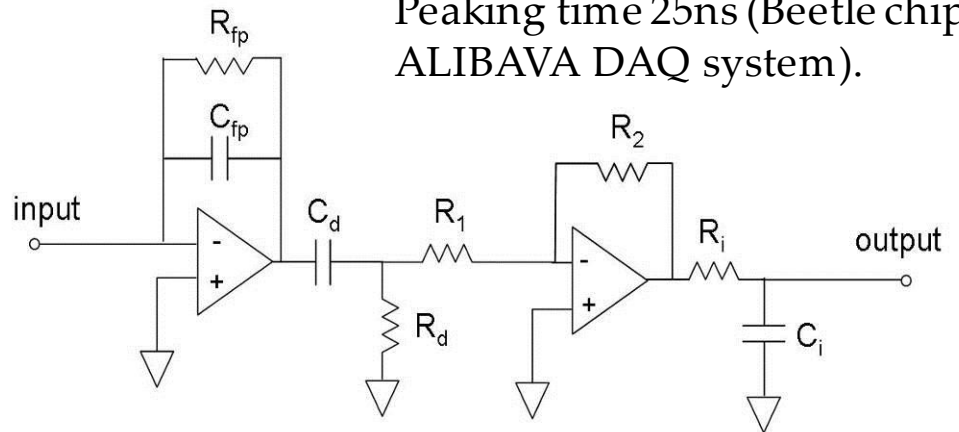


Equivalent Electrical Circuit

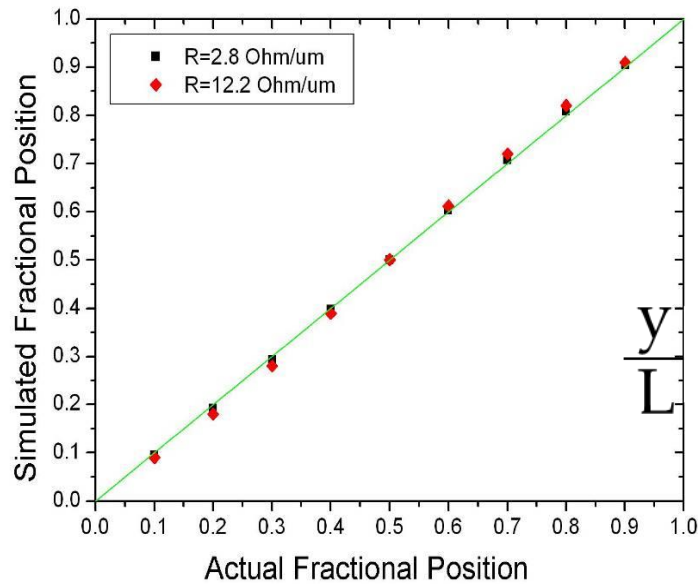
Detector (p⁺-on-n) model ***
80 cells 250 μm long



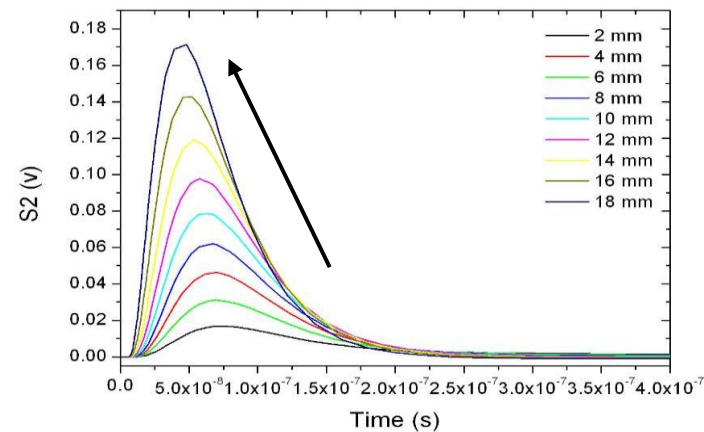
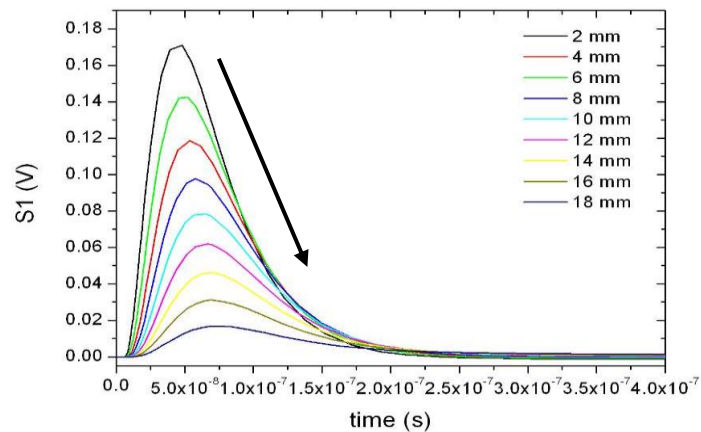
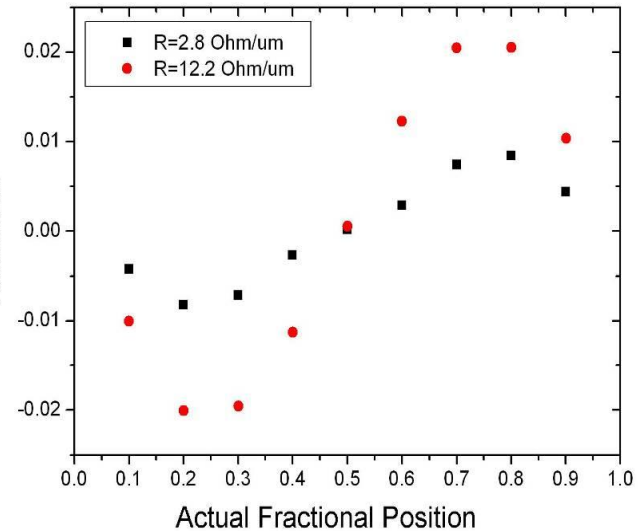
Peaking time 25ns (Beetle chip ALIBAVA DAQ system).



Signal Propagation – Linearity (Simulation)

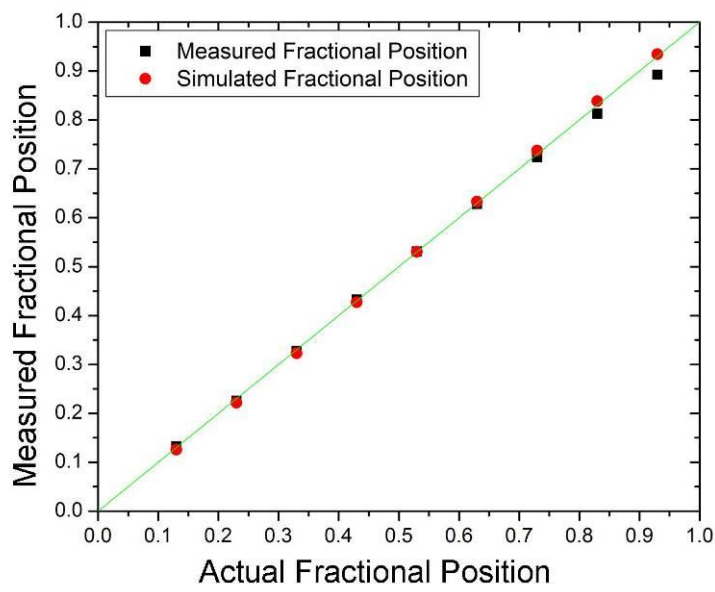


$$\frac{y}{L} = \frac{A_2}{A_1 + A_2} \text{Residuals}$$

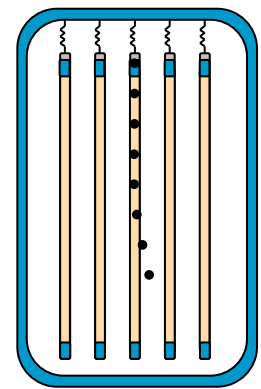




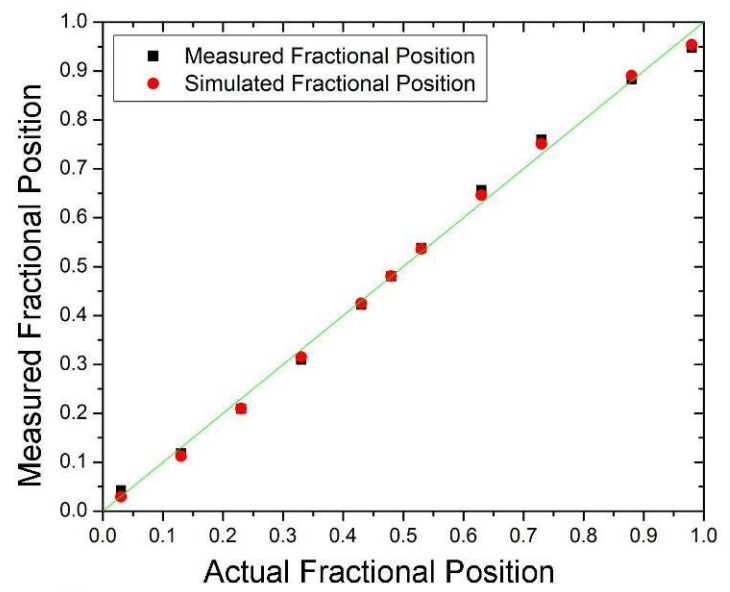
R/l=2.8 Ω/μm



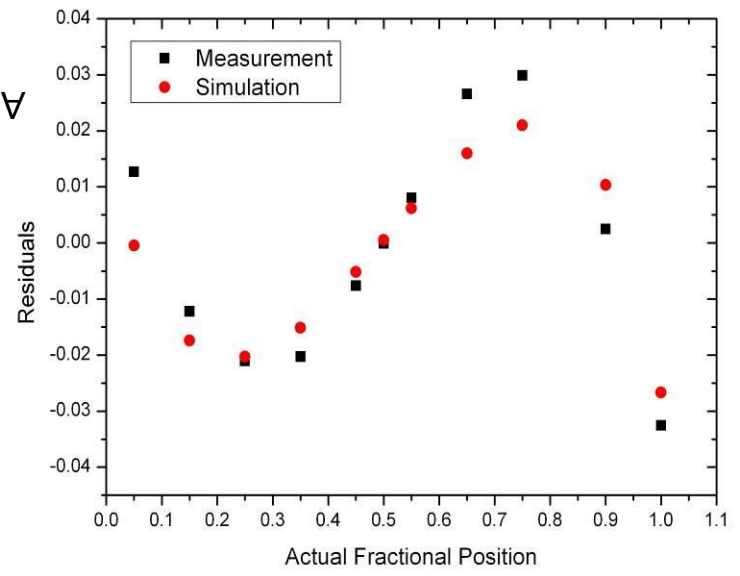
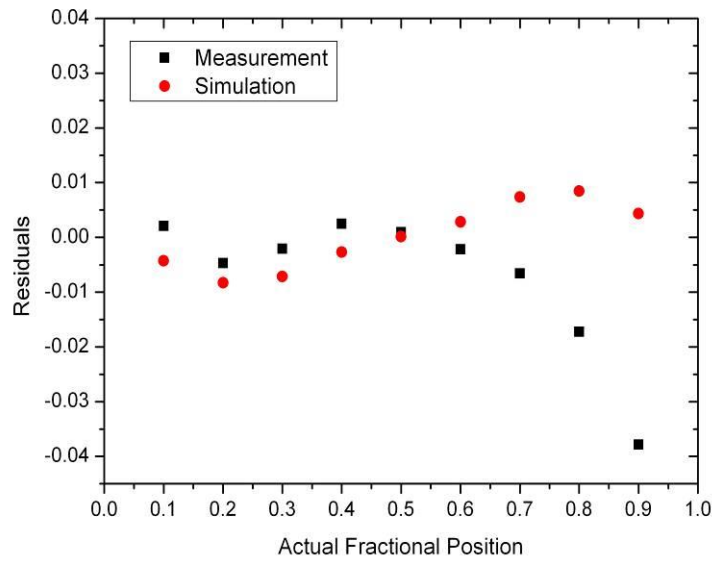
$$\frac{y}{L} = \frac{A_2}{A_1 + A_2}$$



R/l=12.2 Ω/μm



20000 events √ measurement



Longitudinal spatial resolution for 6 MIPs signal

$$\frac{A_2}{A_1+A_2}$$

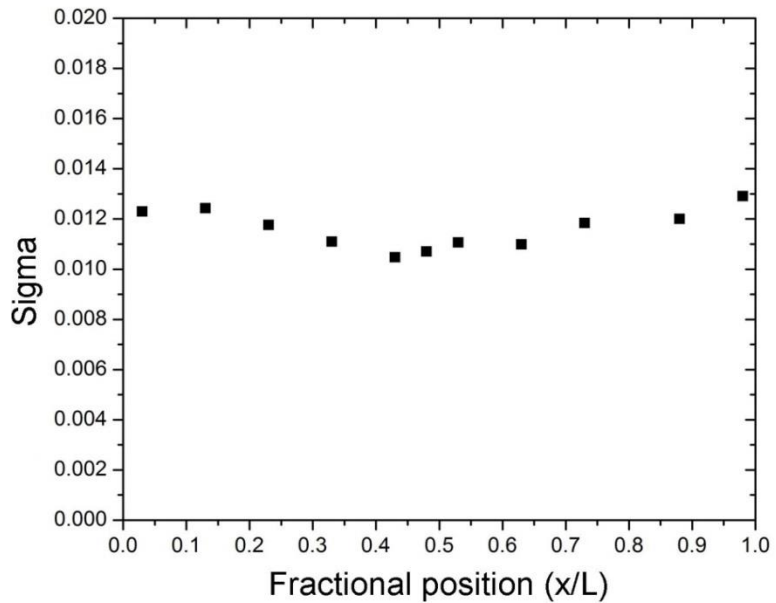
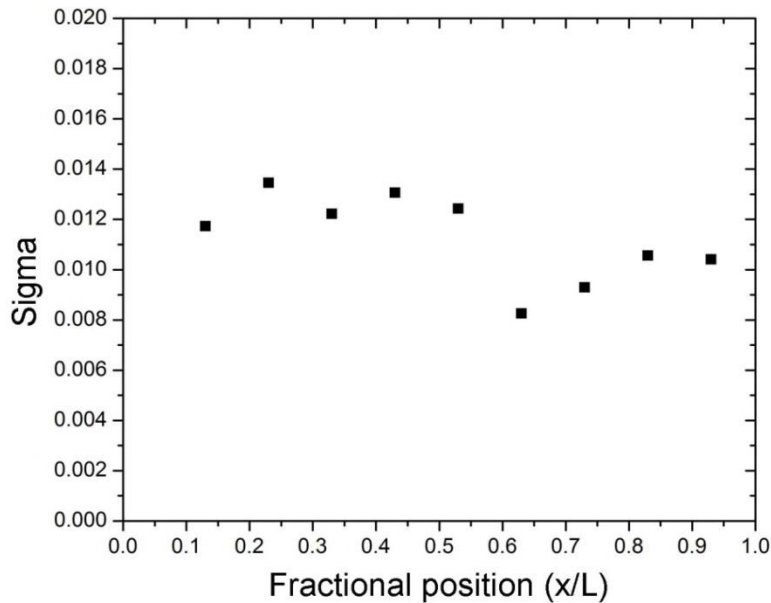
$$\sigma = \frac{A_1 A_2}{(A_1 + A_2)^2} \sqrt{\left(\frac{\sigma_{A_1}}{A_1}\right)^2 + \left(\frac{\sigma_{A_2}}{A_2}\right)^2 - 2\rho \left(\frac{\sigma_{A_1}}{A_1} \frac{\sigma_{A_2}}{A_2}\right)},$$

1.1% L => 220 μm

R/l=2.8 $\Omega/\mu\text{m}$

1.2% L => 240 μm

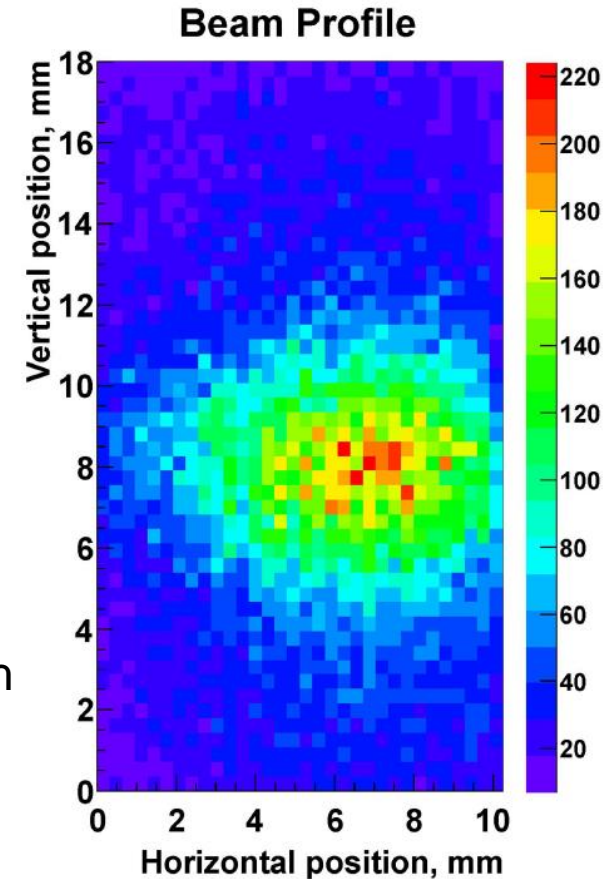
R/l=12.2 $\Omega/\mu\text{m}$



Test Beam Characterization

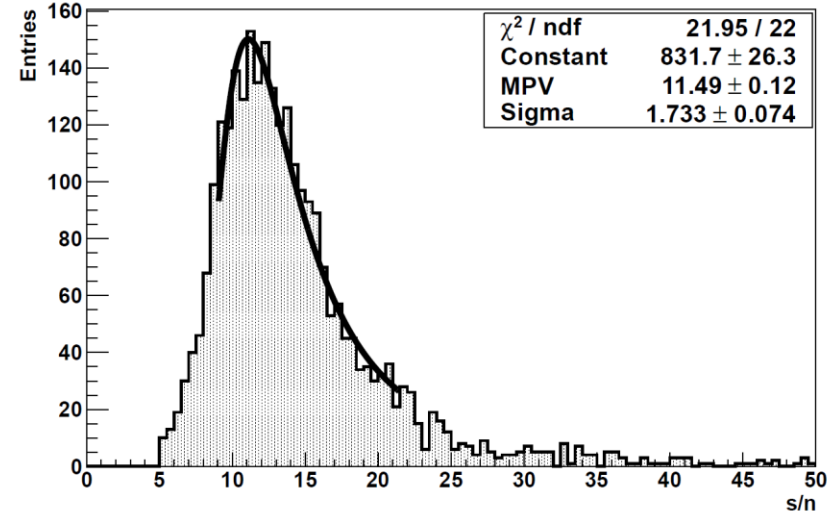
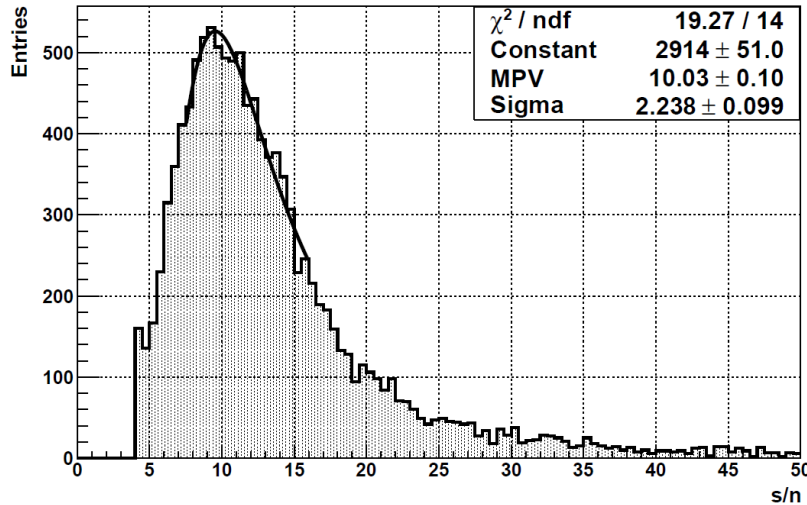


- Test beam at CERN SPS Pion Beam, Nov 2012
- First successful integration and synchronization with AIDA MIMOSA pixel telescope
- Preliminary results:
 - Monitoring of beam profile.
- Currently in progress:
 - Efficiency and resolution using tracking information.

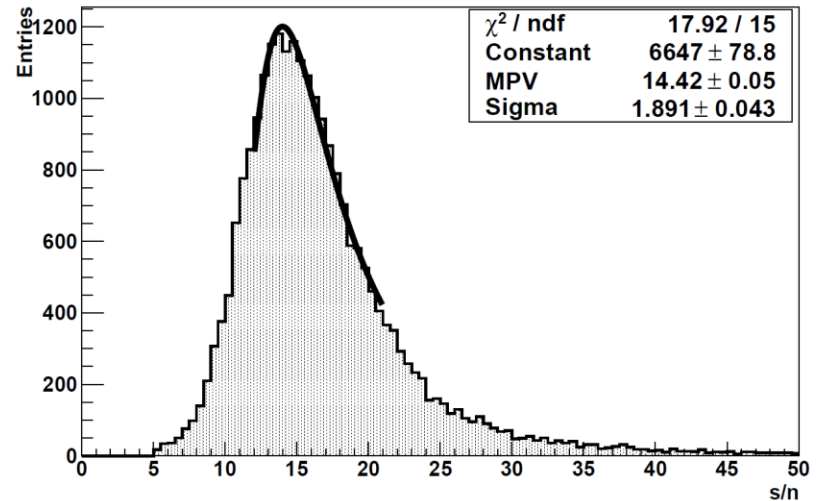
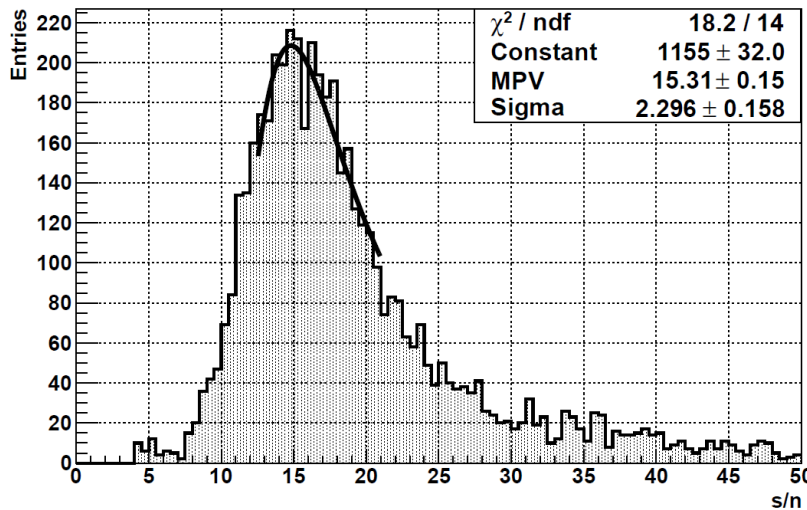


s/n test beam vs s/n radioactive source

Resistive strips detector



Conventional strips detector



SEGMENTED P-TYPE SENSORS WITH CHARGE AMPLIFICATION



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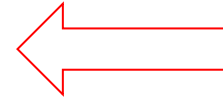
Charge Multiplication- pixel detectors



We are starting the fabrication of new p-type pixel detectors with enhanced multiplication effect in the n-type electrodes, very low collection times and with no cross-talk.

Three different approaches:

1. Thin p-type epitaxial substrates
2. Low gain avalanche detectors
3. 3D with enhanced electric field.



Two projects funded by CERN RD50 collaboration to work on these technologies.

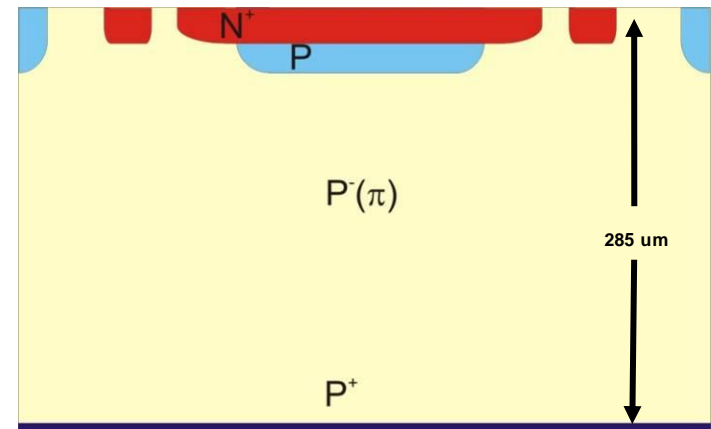
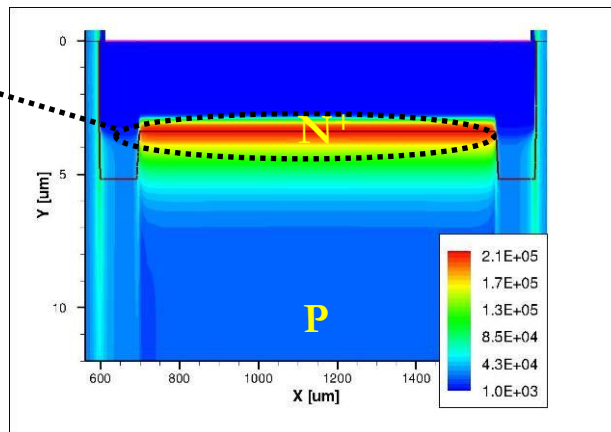
<http://rd50.web.cern.ch/rd50/>

Low gain avalanche detectors (LGAD)

Implating an $n^{++}/p^{+}/p^{-}$ junction along the centre of the electrodes. Under reverse bias conditions, a high electric field region is created at this localised region, which can lead to a multiplication mechanism (impact ionization).

Advantages = Thinning while keeping same S/N as standard detectors.

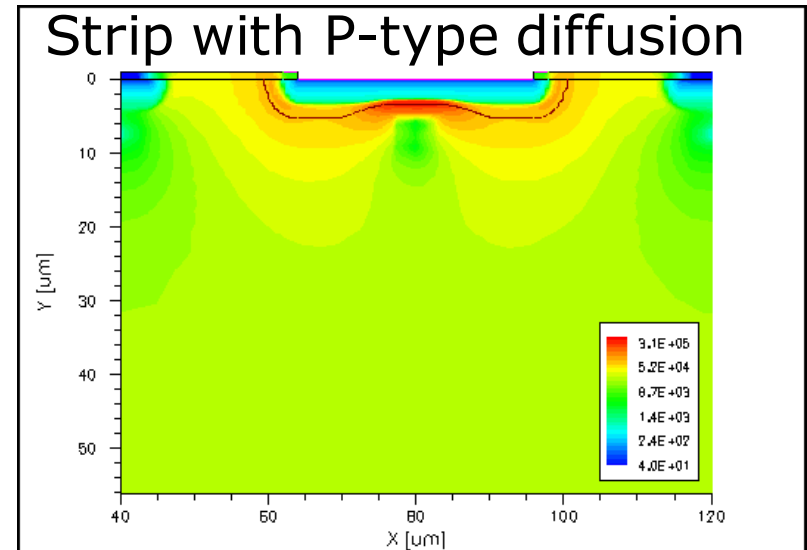
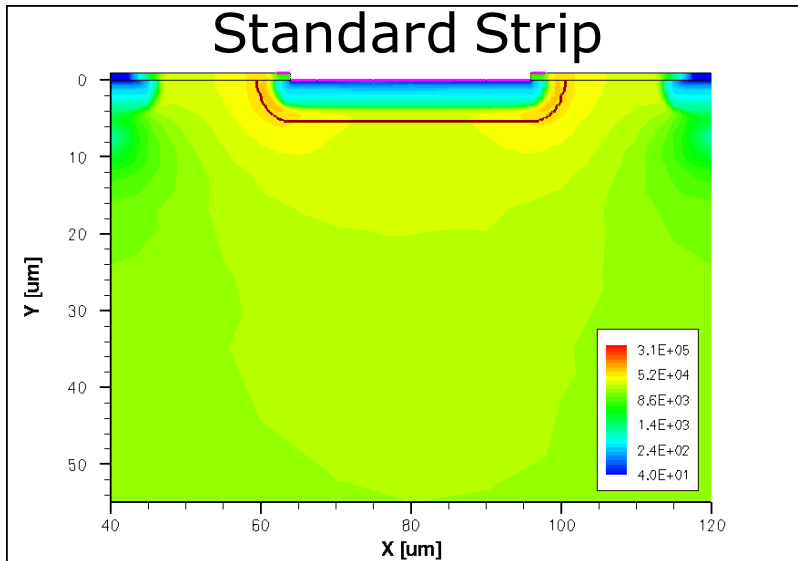
High Electric Field region leading to multiplication



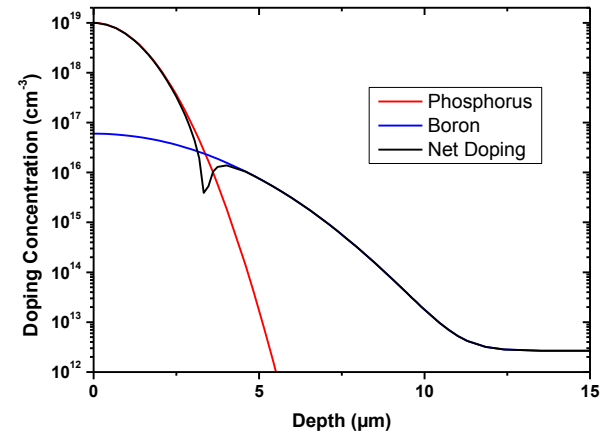
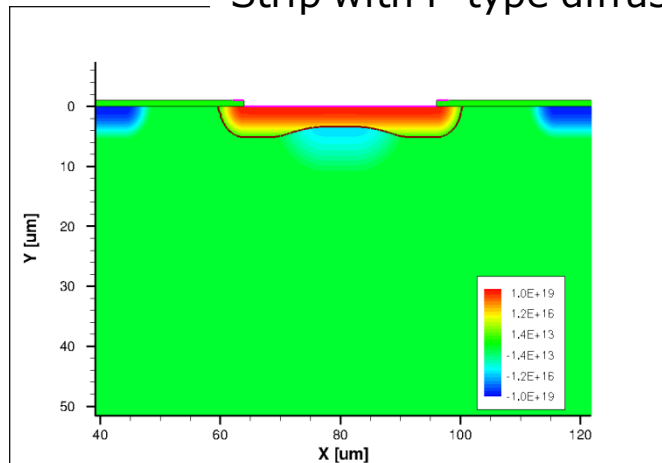
P. Fernandez et al, "Simulation of new p-type strip detectors with trench to enhance the charge multiplication effect in the n-type electrodes", Nuclear Instruments and Methods in Physics Research A 658(2011) 98–102.

Simulation of the Electric Field

- To obtain the manufacture parameters (doping profiles)



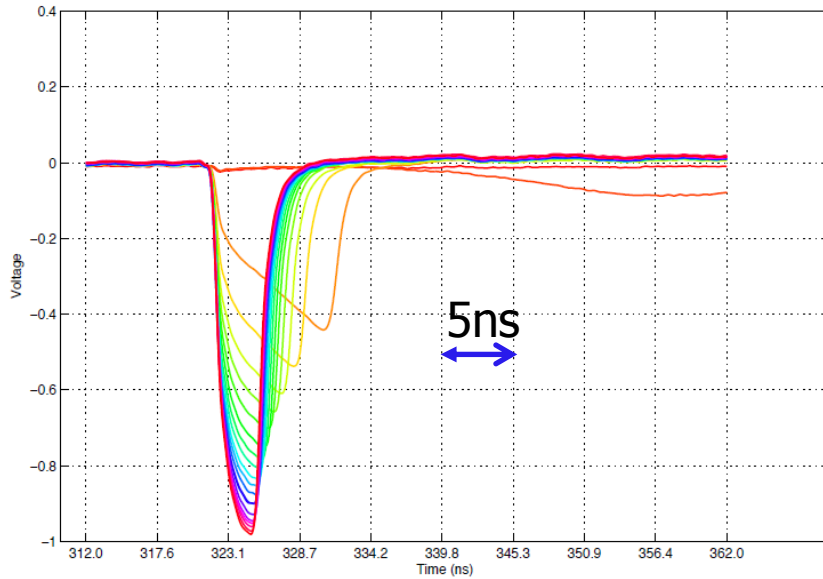
Strip with P-type diffusion: 2D and 1D doping profiles



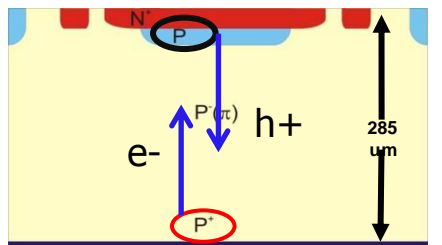
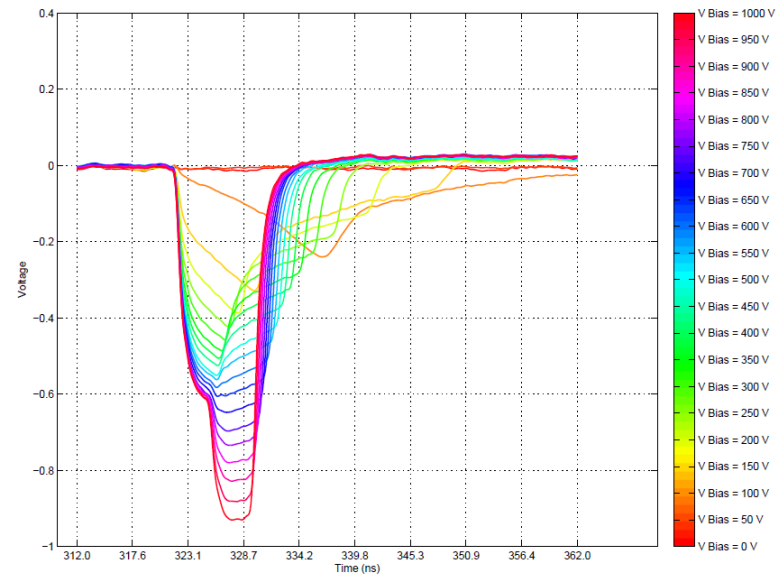
Red laser TCT characterization

Bottom injection

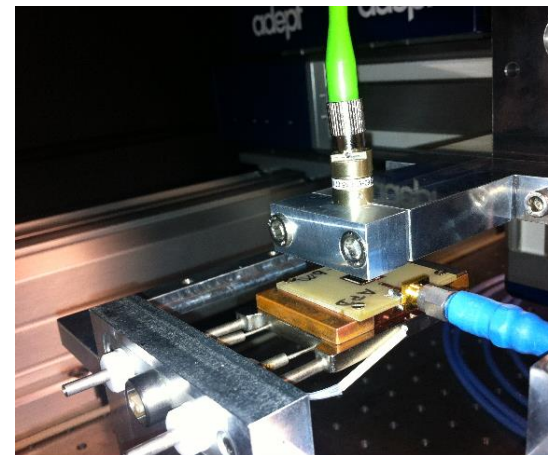
Standard diode n on p



P-type diffusion diode



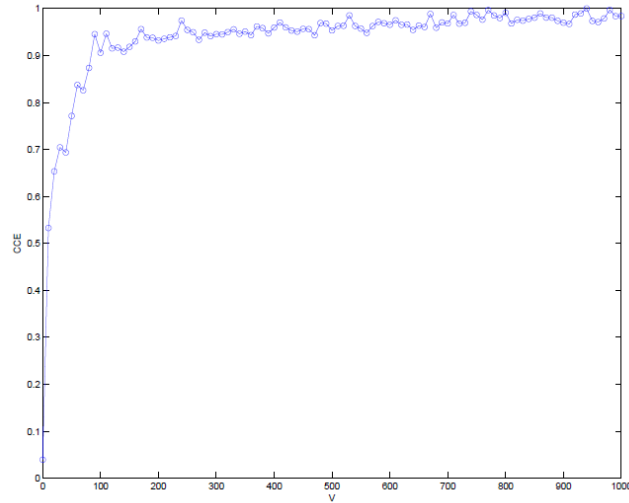
Red laser
(1060 nm)



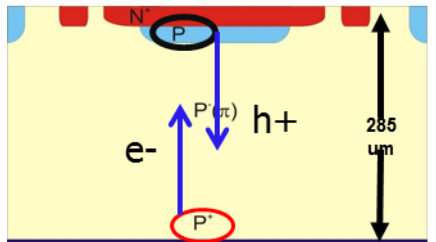
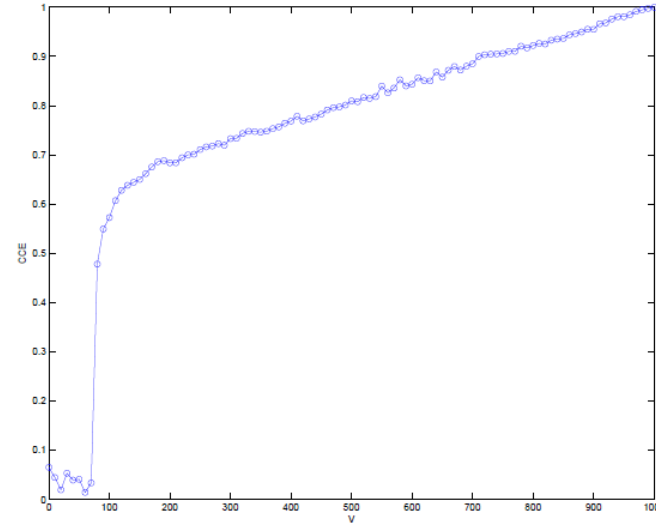
Red laser TCT characterization

Charge collection efficiency

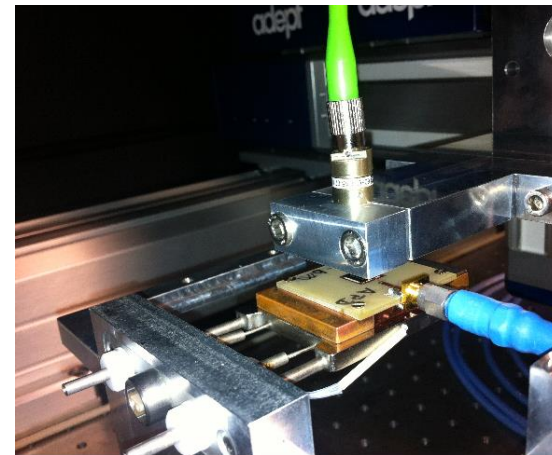
Standard diode



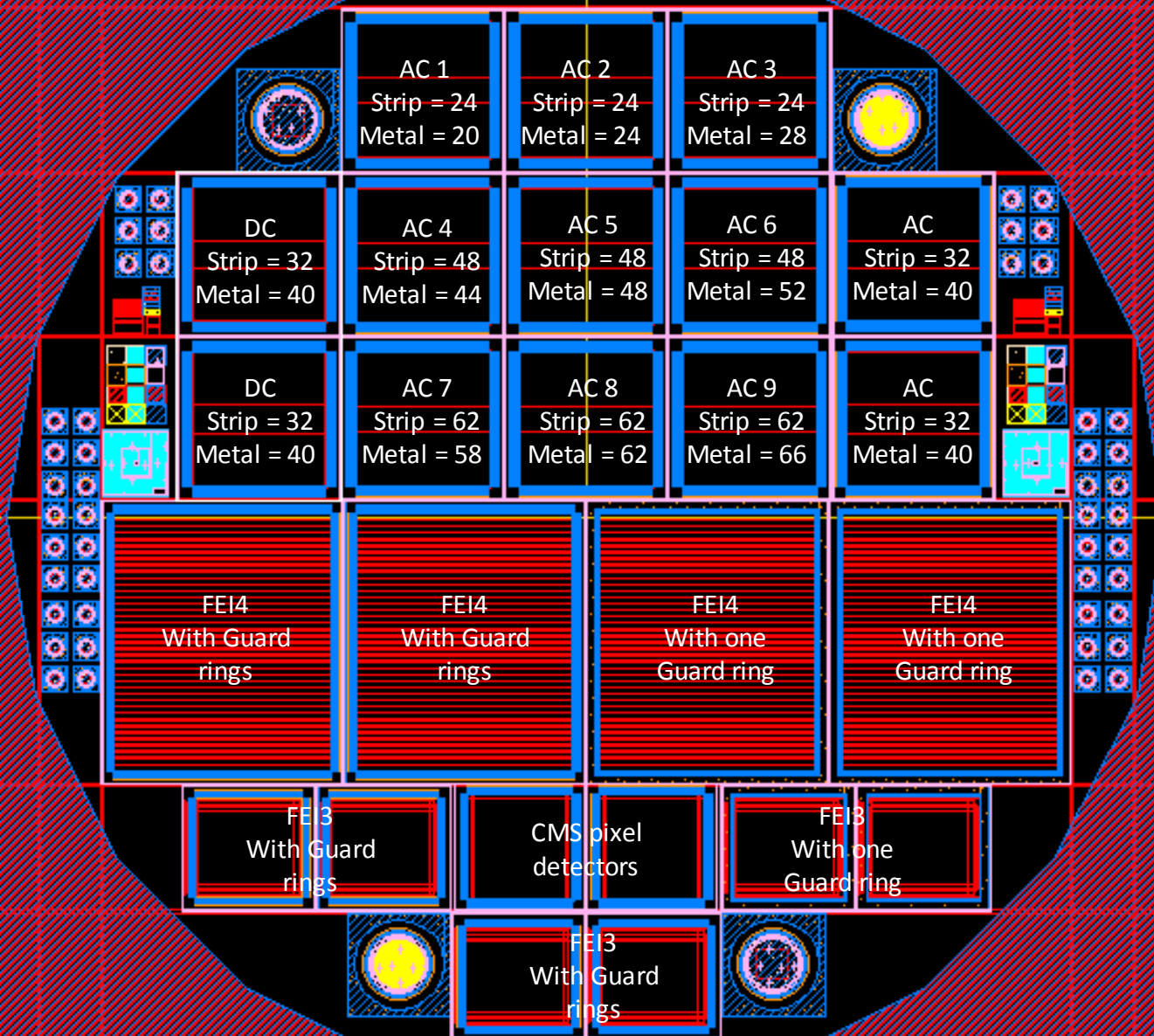
P-type diffusion diode



Red laser
(1060 nm)



Mask set (planar)

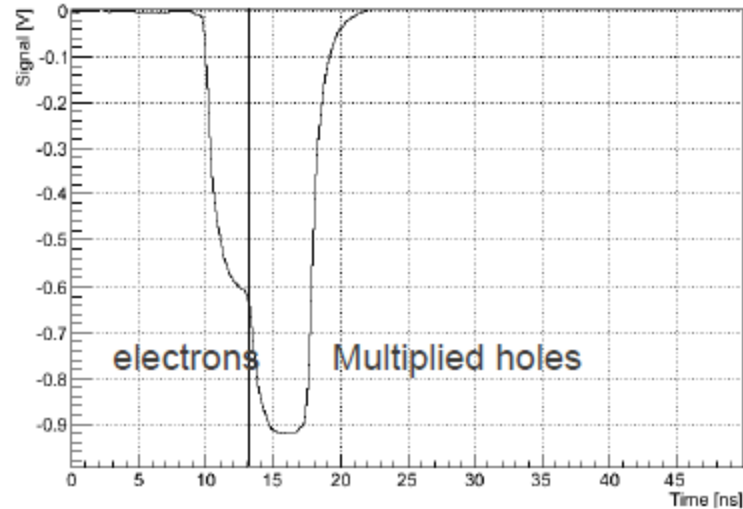


Summary

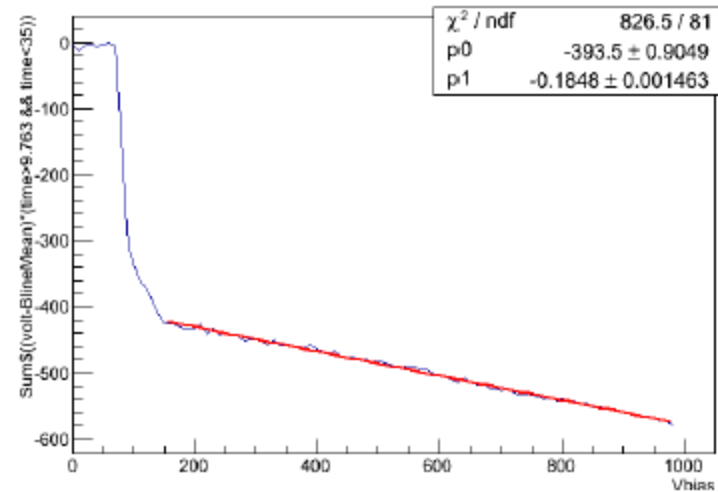


- A novel 2D position-sensitive semiconductor detector concept based on the resistive charge-division readout method has been introduced.
- The initial results demonstrates the feasibility of the charge division method in a fully fledged microstrip sensor.
- Test-beam studies on detection of minimum ionizing particles are in progress
- The effect of charge multiplication has been observed within RD50 and it was started to be investigated systematically.
- New detector designs aim to fabricate detectors with moderate gain and fast collection times.

At $V \gg V_{dep}$ (for instance 980V) the RC tails are short. Check it with simulation:



$$\text{Gain}(V=980) = Q(\text{holes}) / Q(\text{electrons}) = 3$$



Gain at lower voltages, extracted from CCE curve:

$$\text{CCE}(980) / \text{CCE}(140) = \text{Gain}(980) (\text{Gain}(140))$$

Then $\text{Gain}(140) = 2.2$